SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

ABSTRACT OF THE DISCLOSURE

A ball grid array type semiconductor package comprising a semiconductor chip formed with bonding pads, an elastomer bonded to the semiconductor chip, a flexible wiring substrate bonded to the elastomer and formed with wirings connected at one end to the bonding pads of the semiconductor chip, a solder resist formed on the main surface of the flexible wiring substrate and solder bump electrodes connected to the other ends of the wirings, in which the elastomer is bonded to the flexible wiring substrate on the side of the tape, the solder resist is formed on the side of the wirings, and the solder bump electrodes are connected with the wirings by way of the through holes formed in the solder resist.

Figures 2 and 6